

FIG. 1A

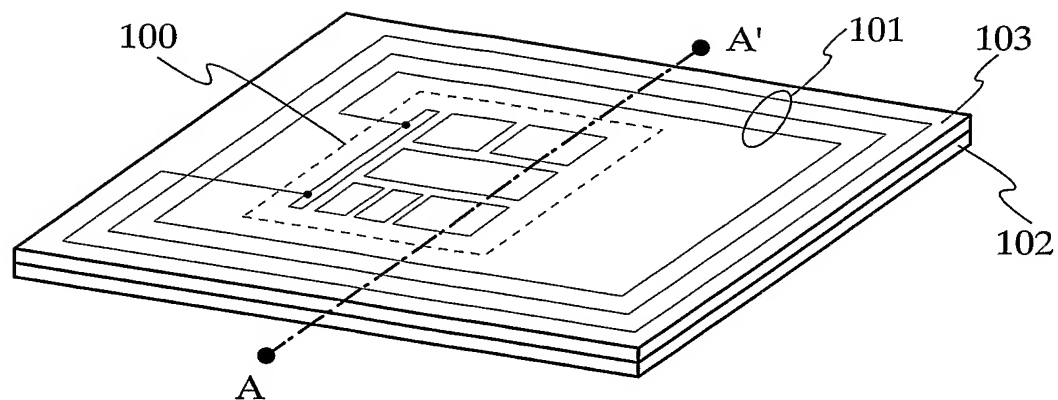


FIG. 1B

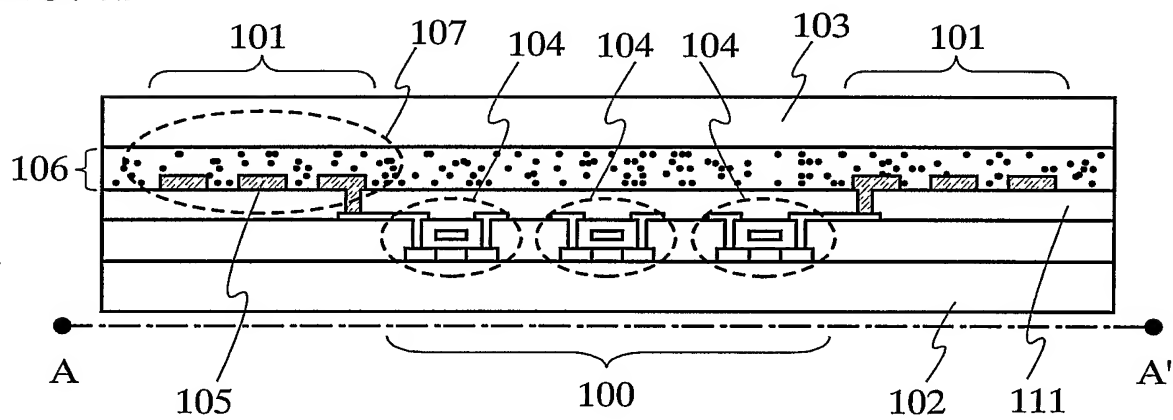


FIG. 1C

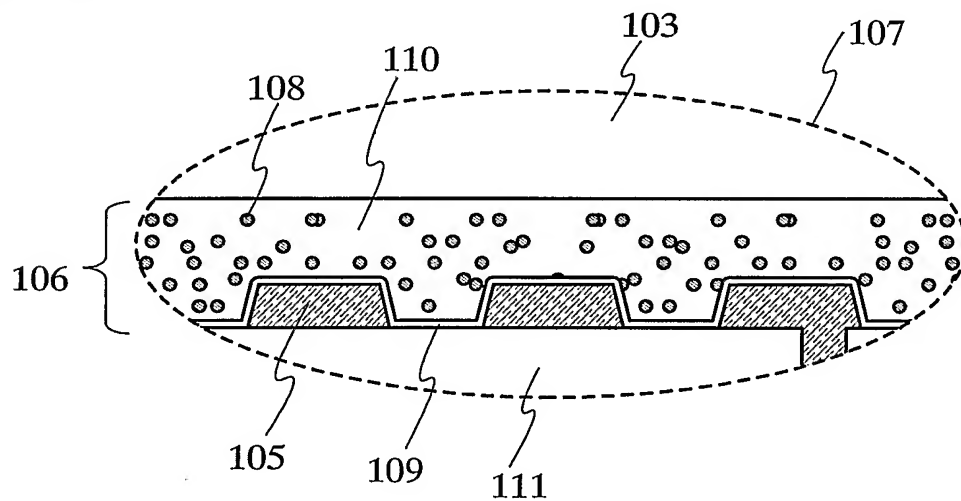


FIG. 2A

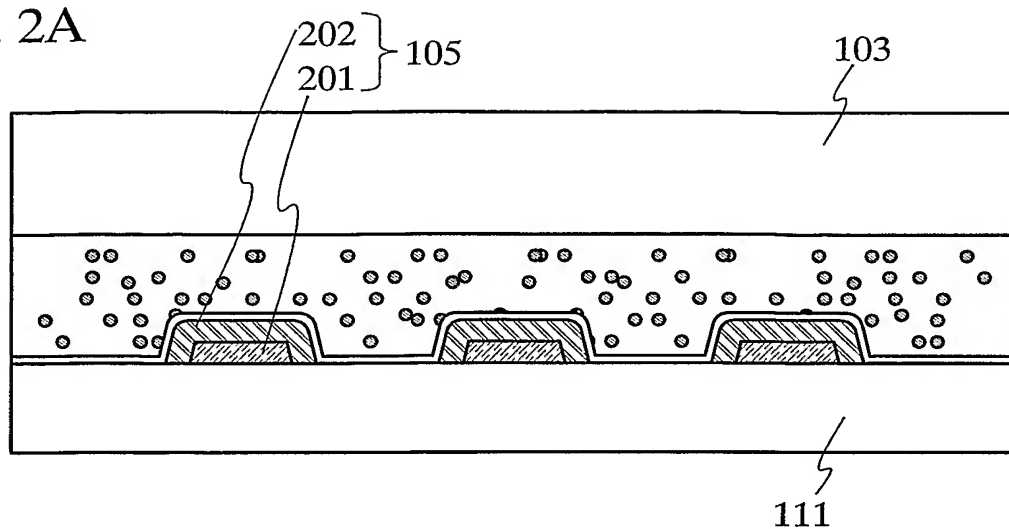


FIG. 2B

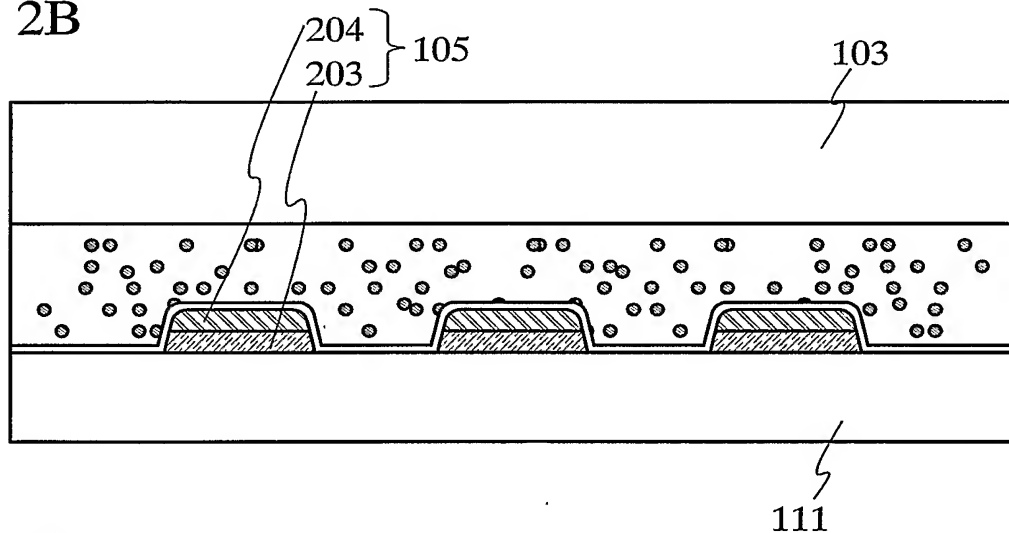


FIG. 2C

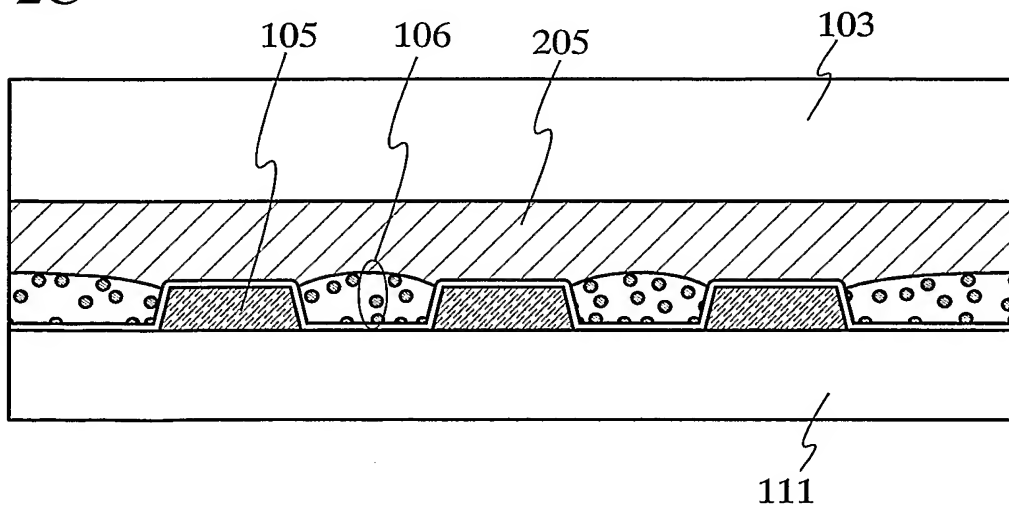


FIG. 3A

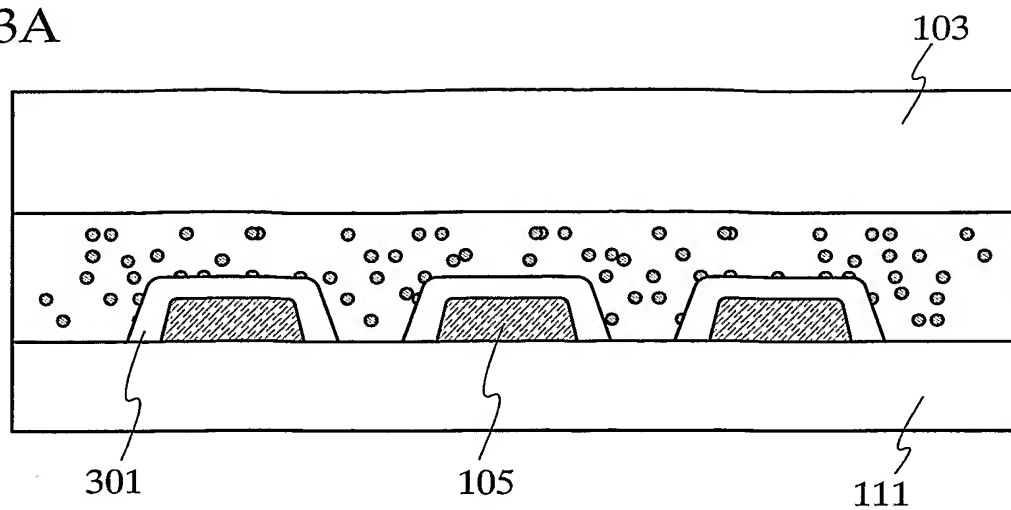


FIG. 3B

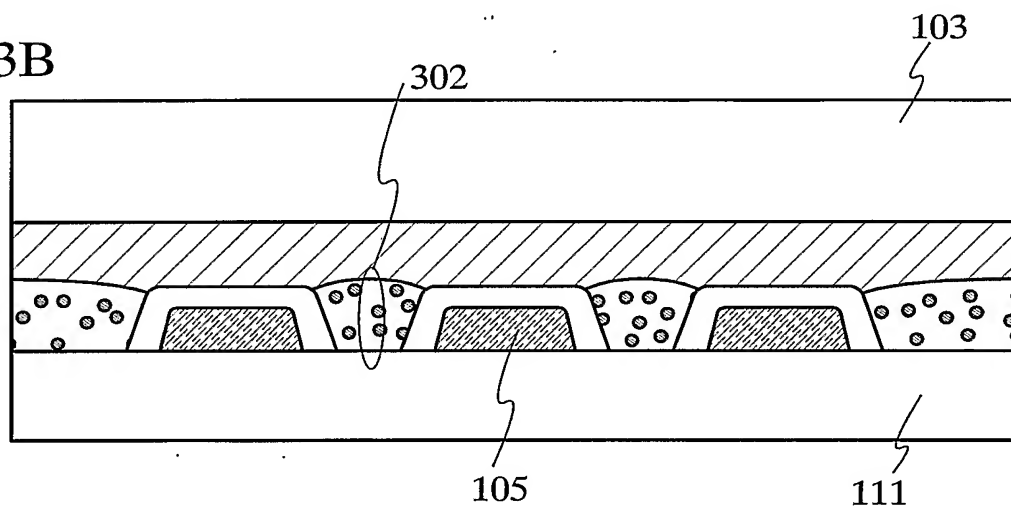


FIG. 3C

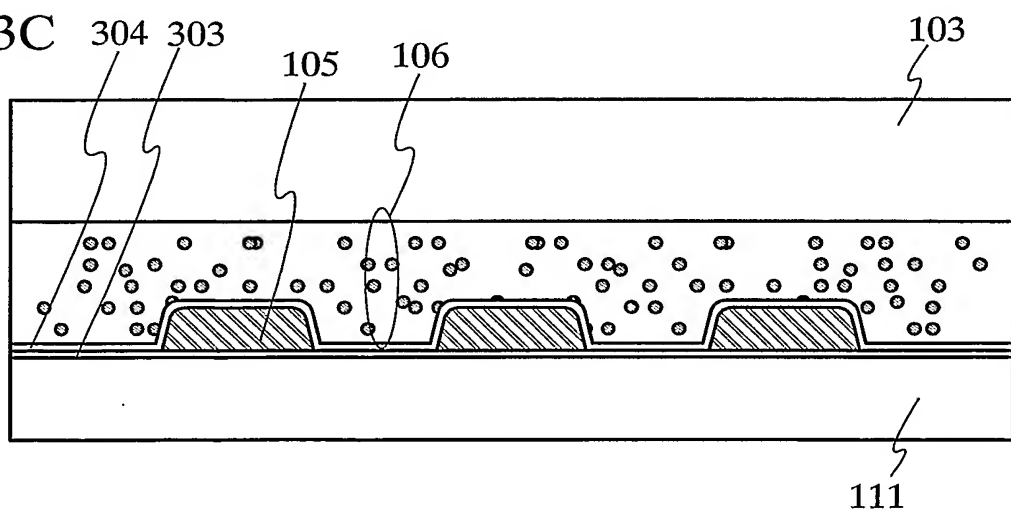


FIG. 4A

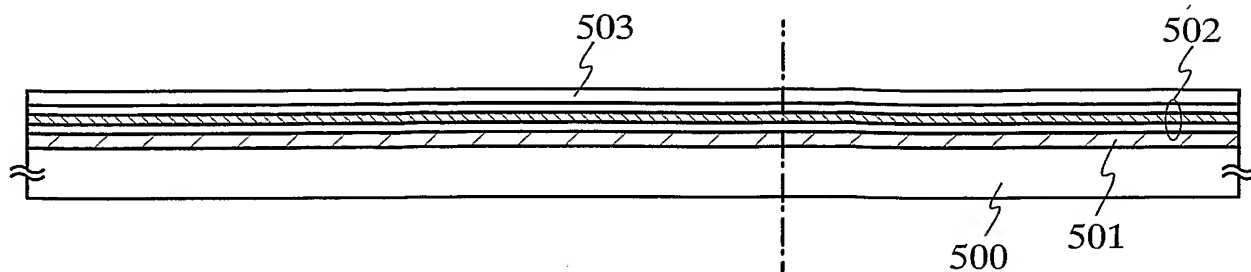


FIG. 4B

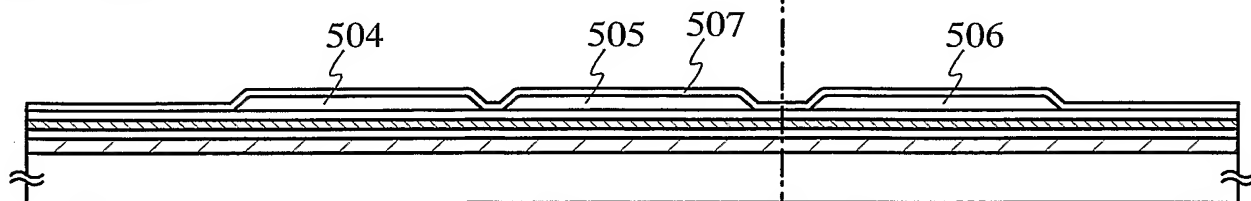


FIG. 4C

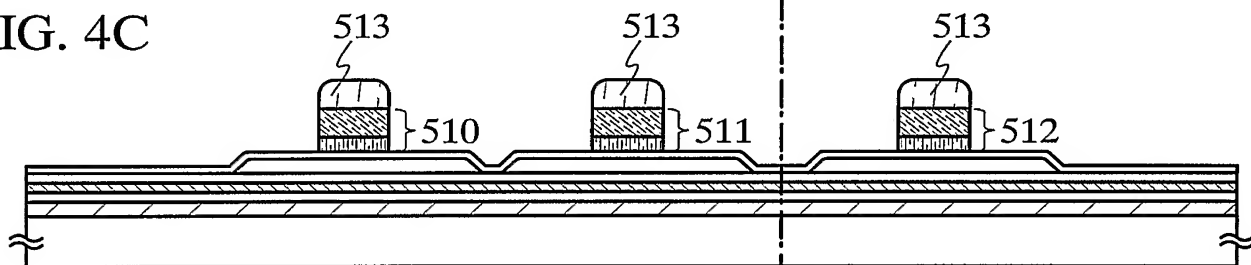


FIG. 4D

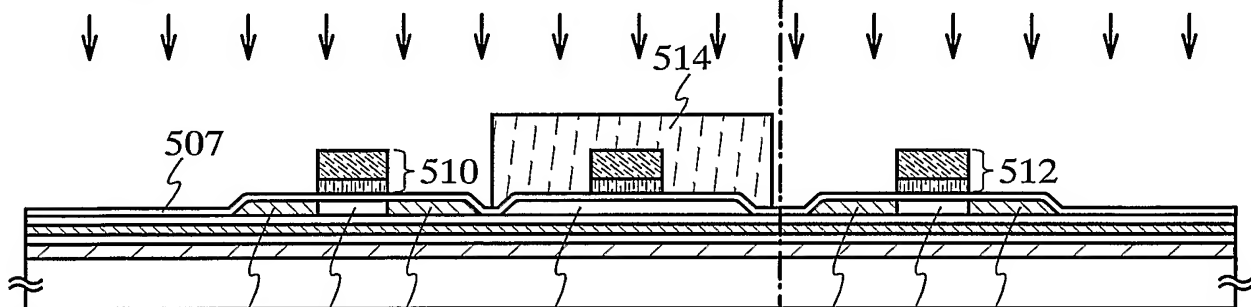


FIG. 4E

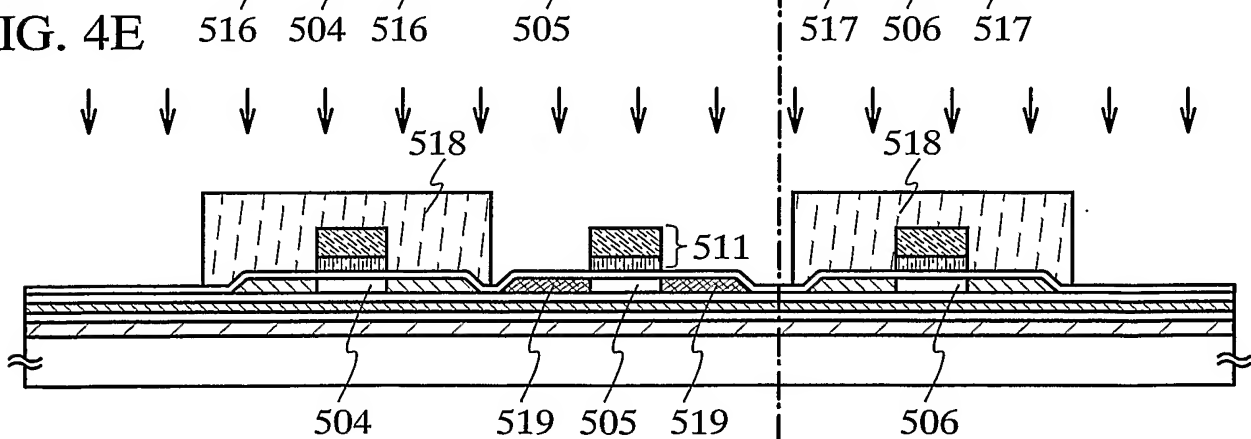


FIG. 5A

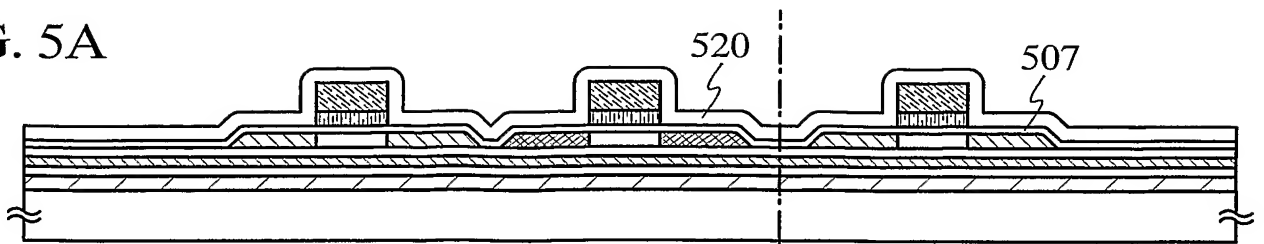


FIG. 5B

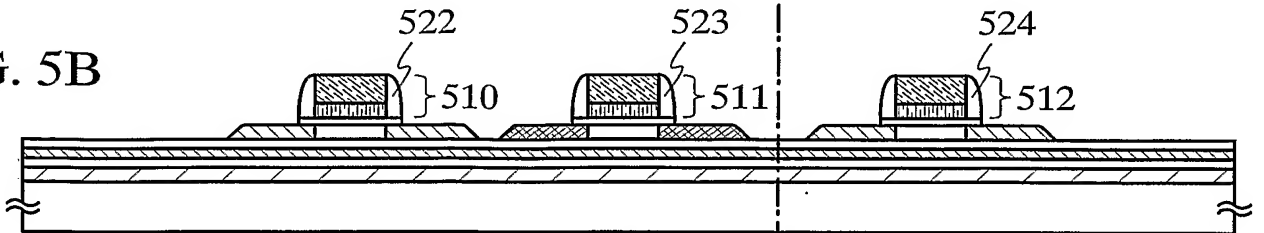


FIG. 5C

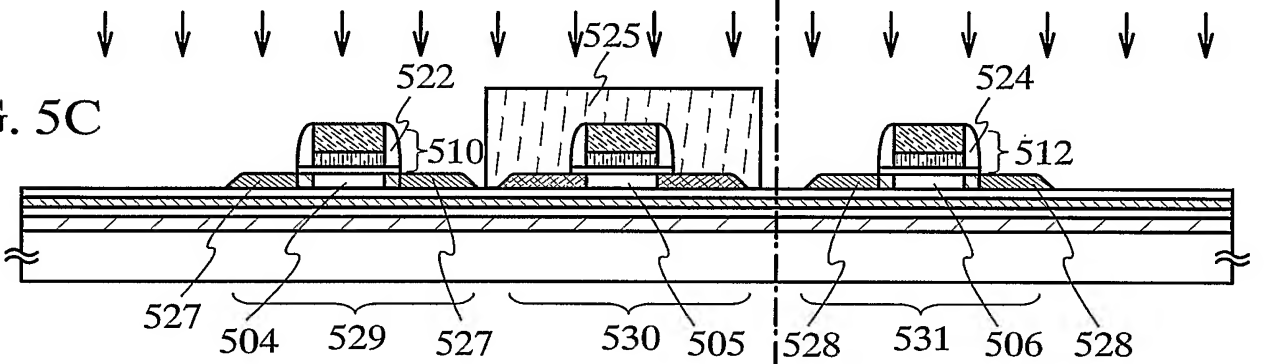


FIG. 5D

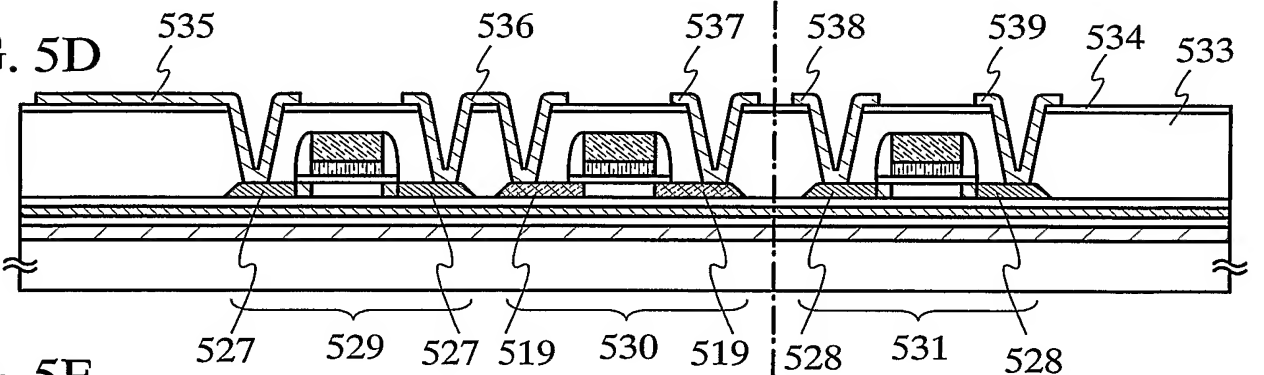


FIG. 5E

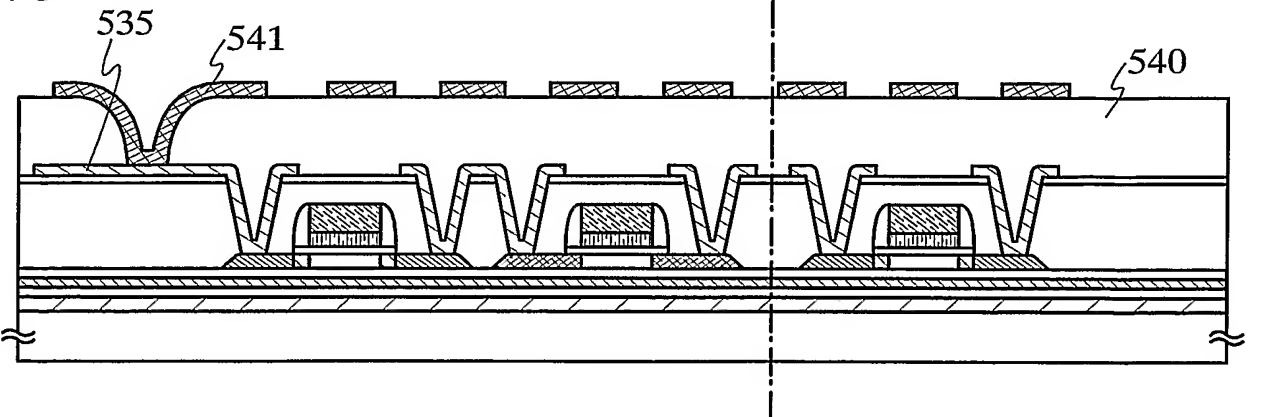


FIG. 6A

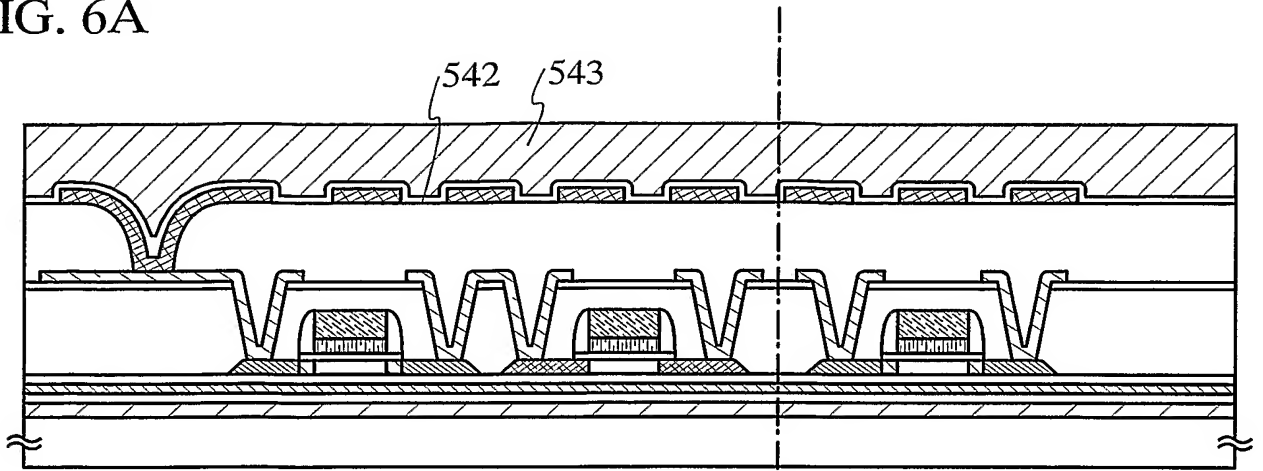


FIG. 6B

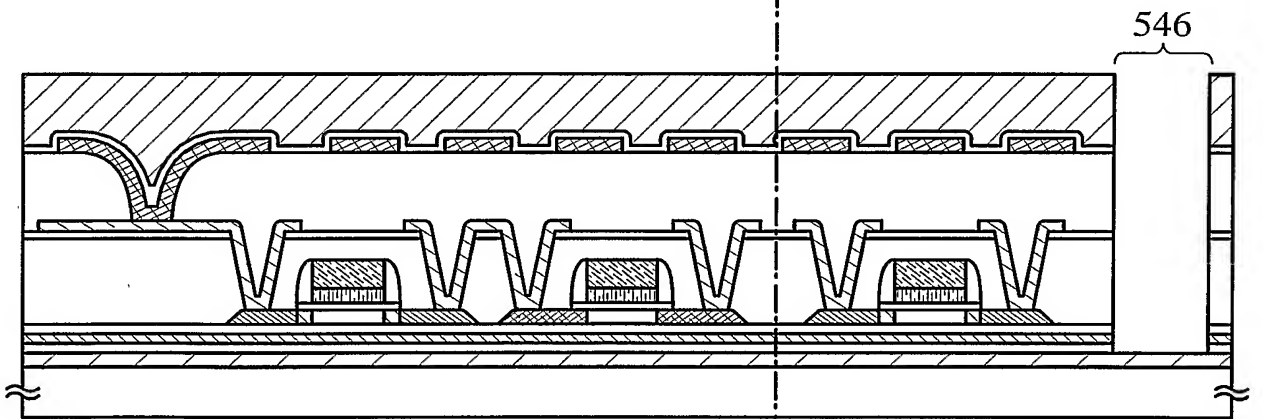


FIG. 6C

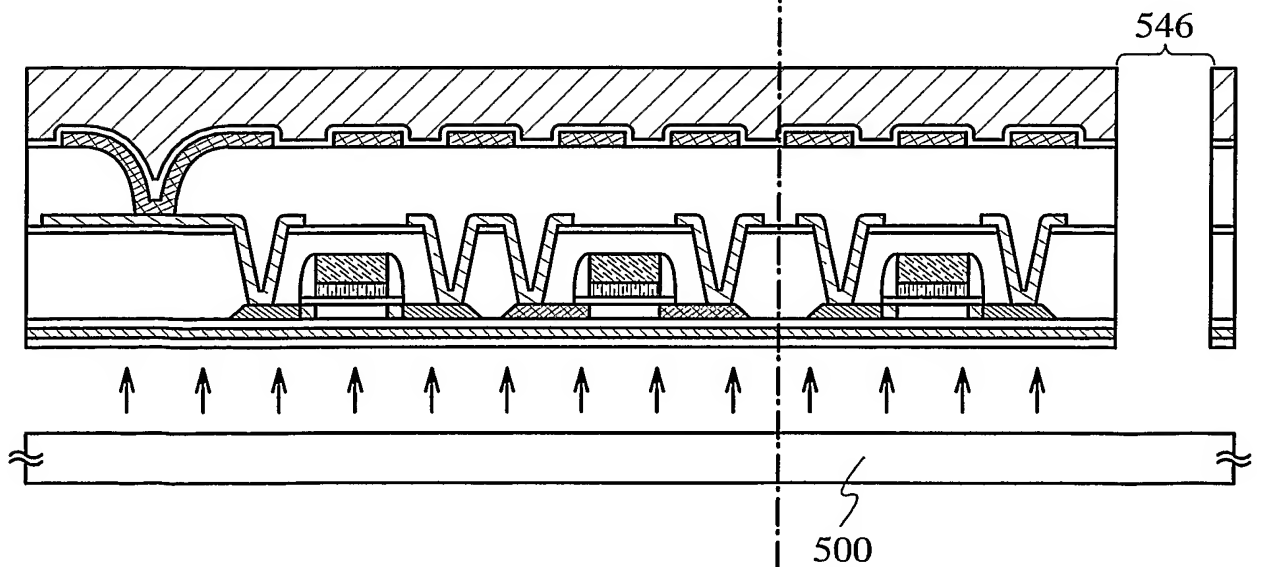


FIG. 7A

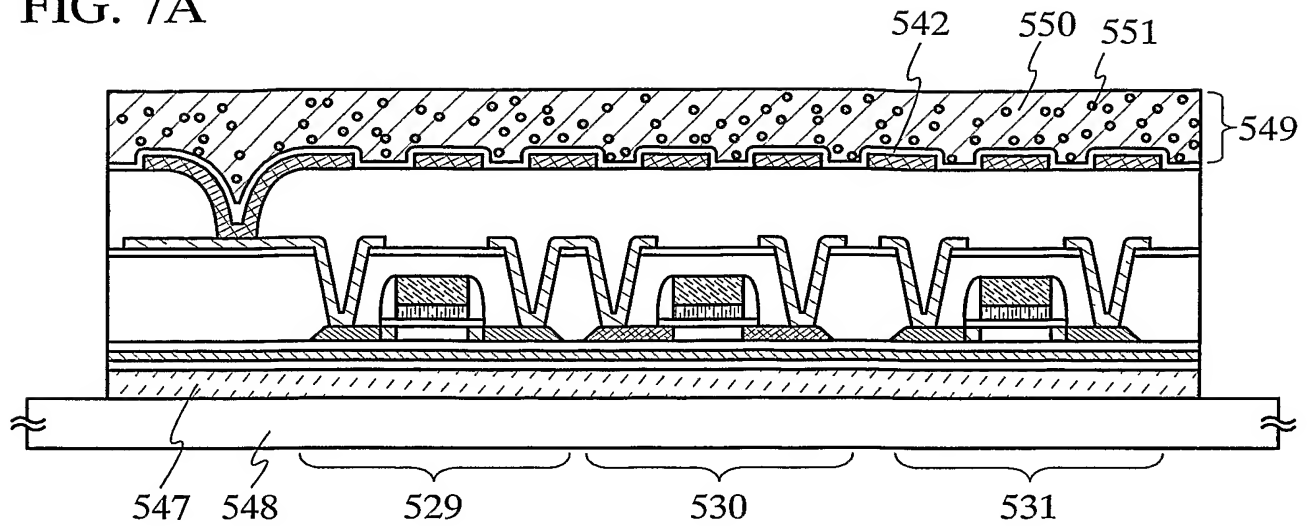
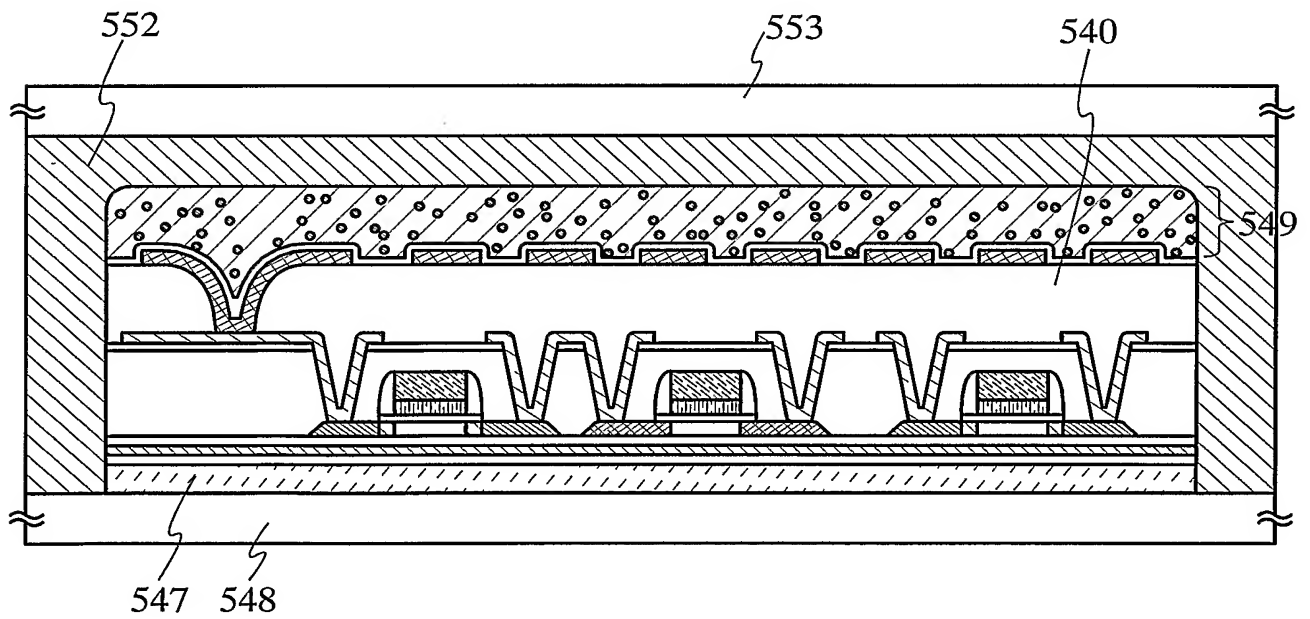


FIG. 7B



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FIG. 8

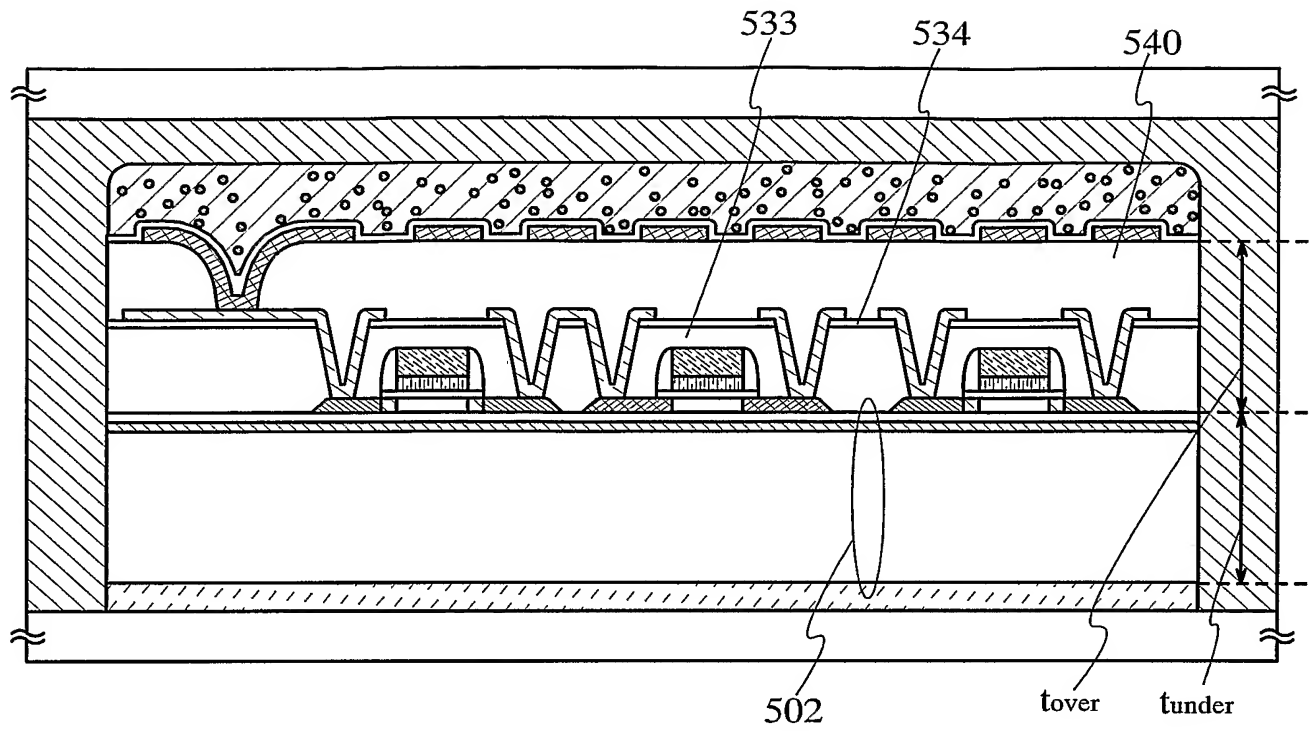


FIG. 9A

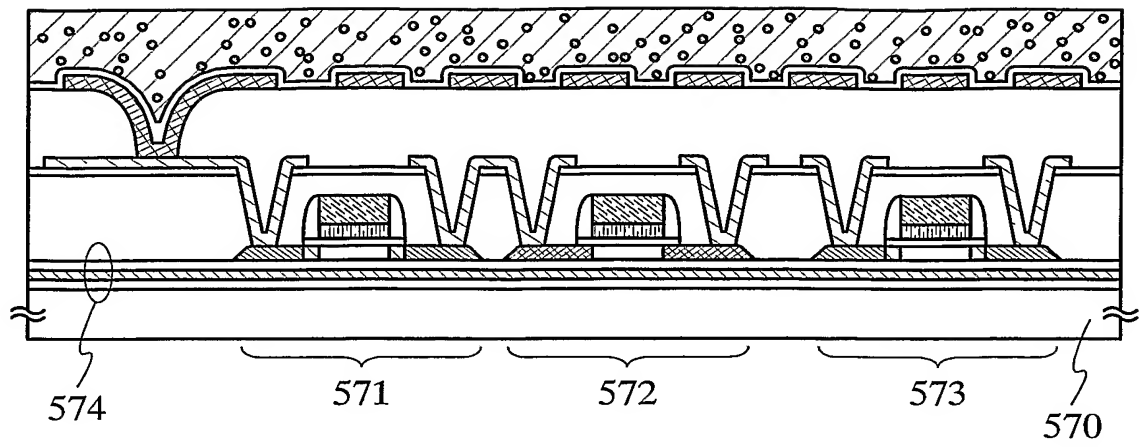


FIG. 9B

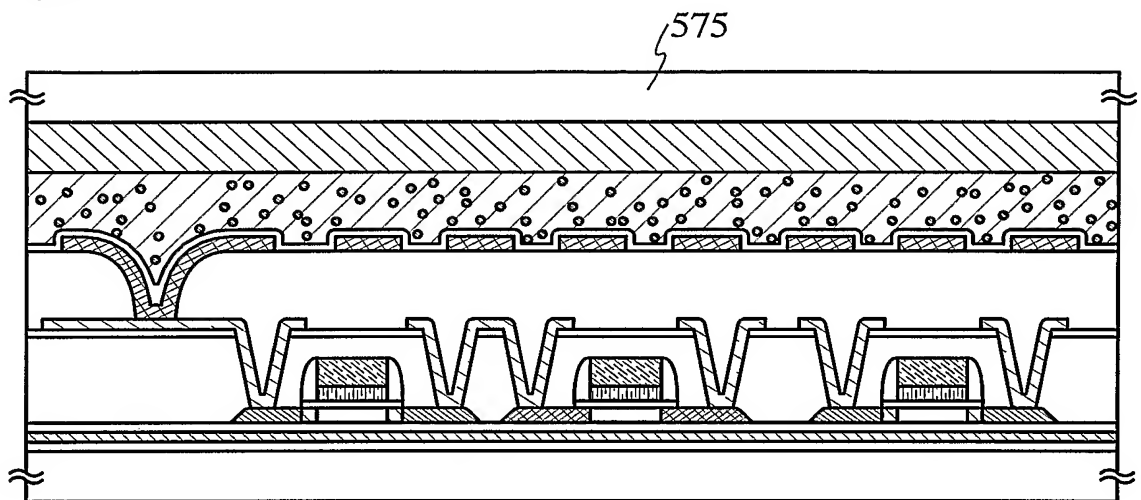


FIG. 10A

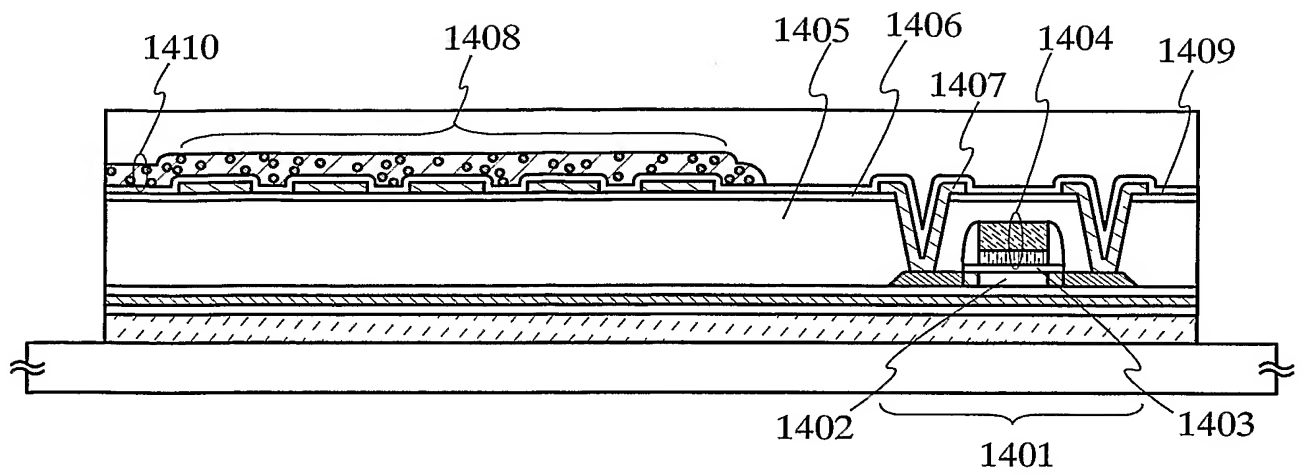
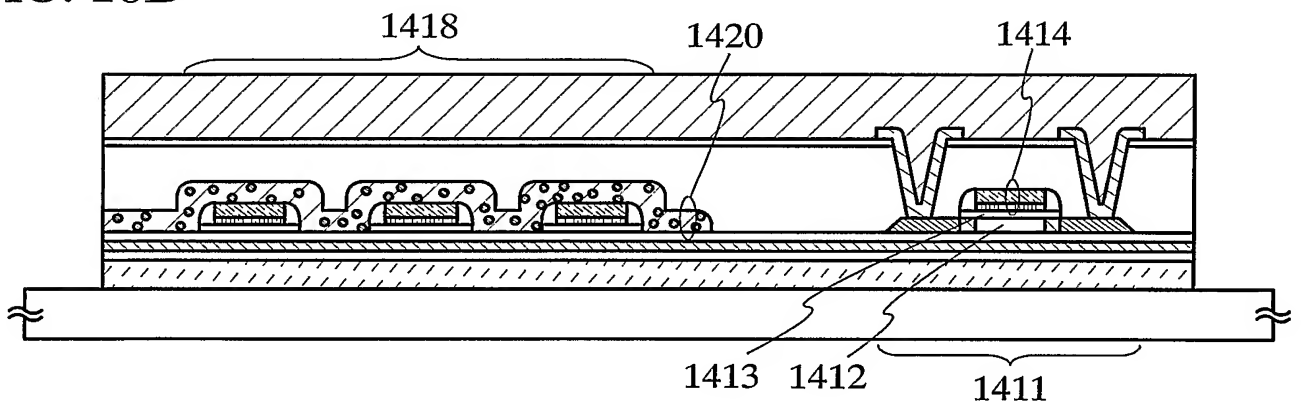


FIG. 10B



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FIG. 11

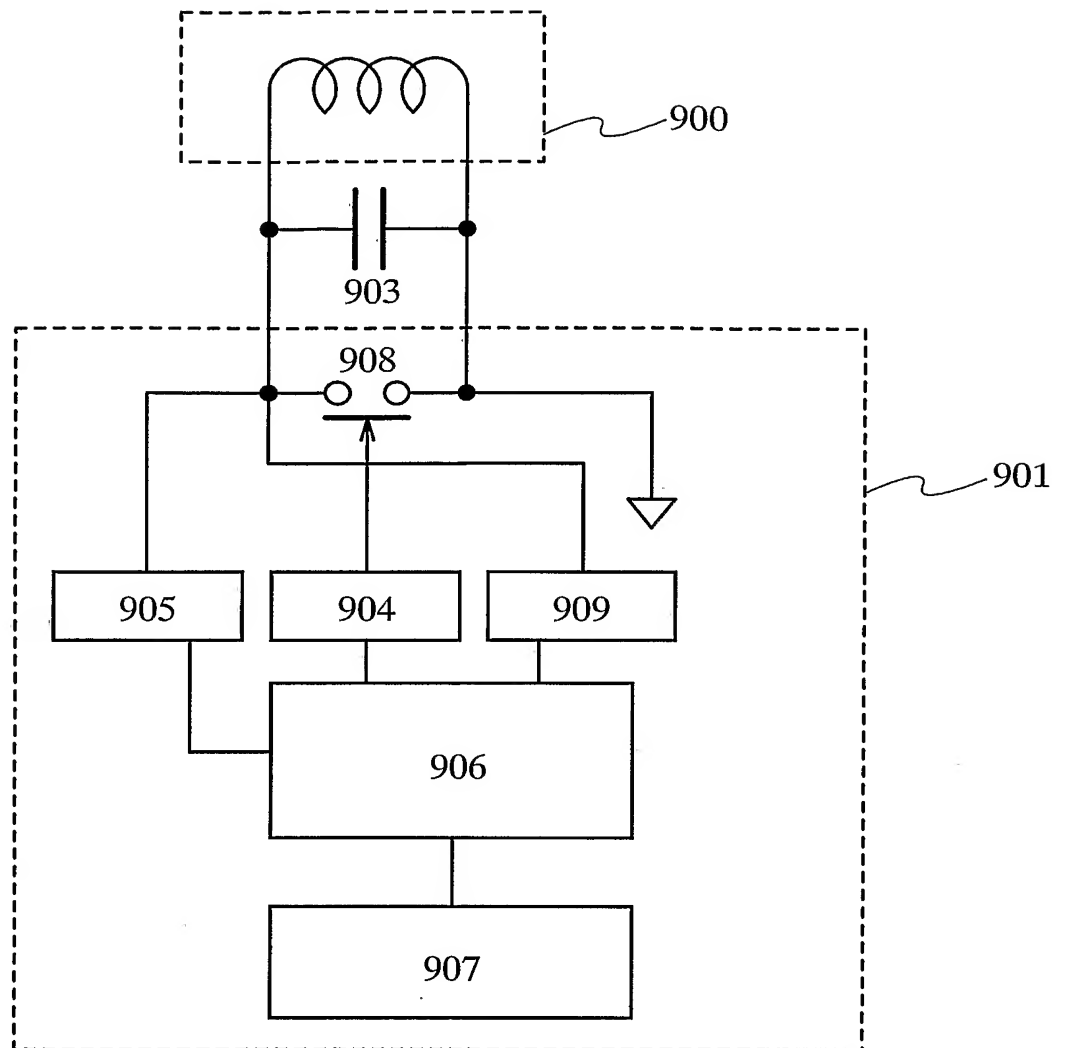


FIG. 12A

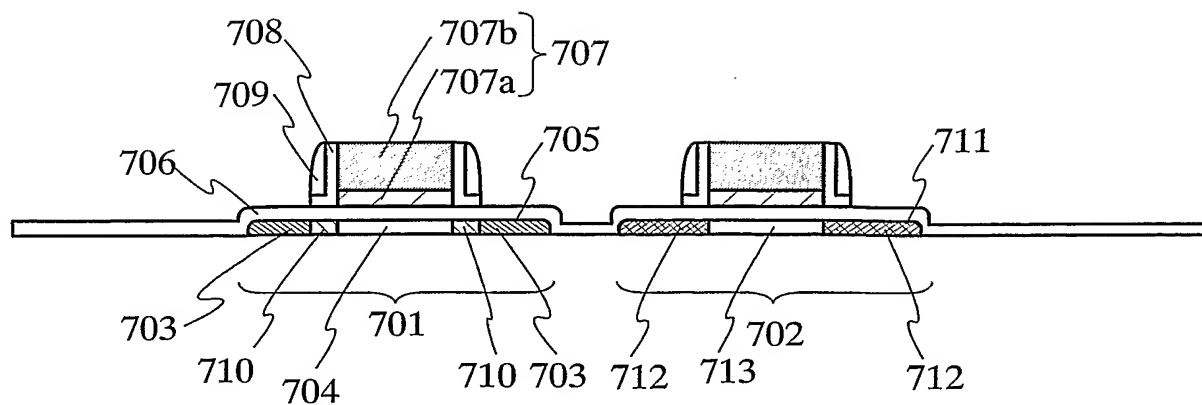


FIG. 12B

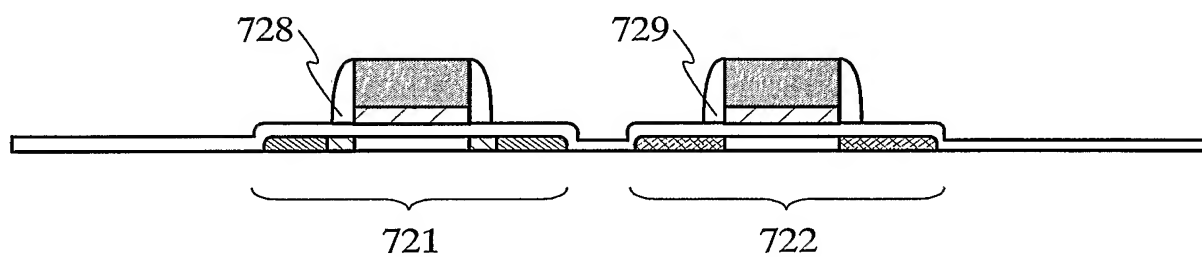


FIG. 12C

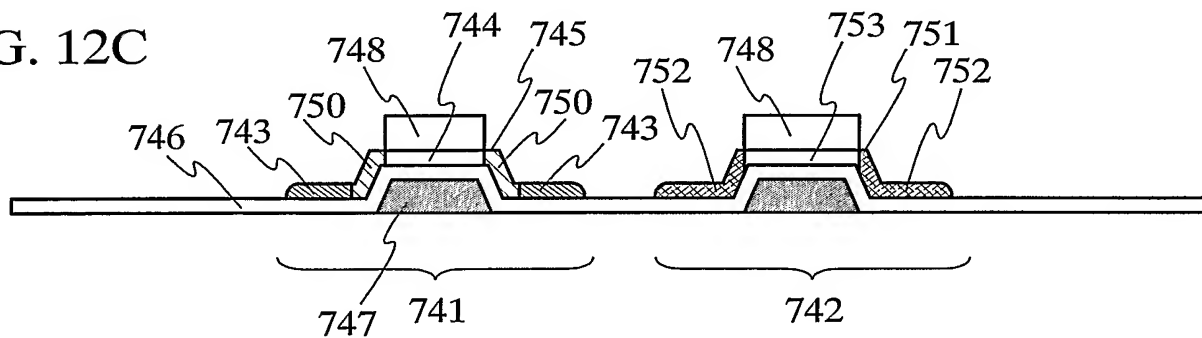


FIG. 13A

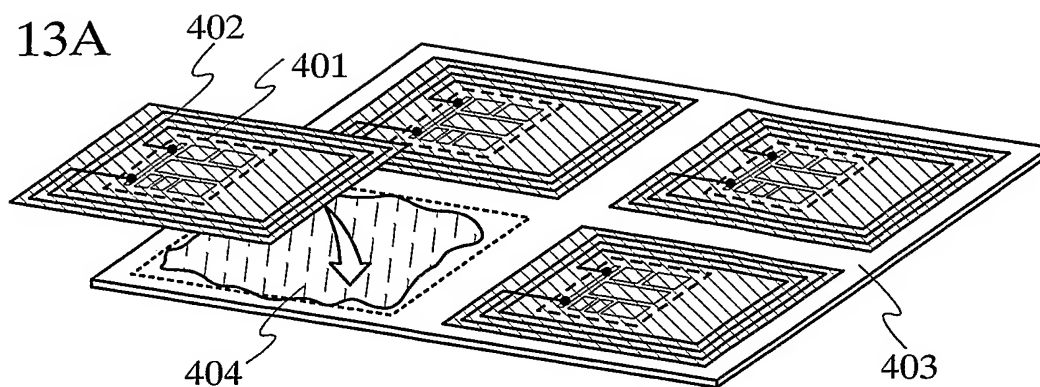


FIG. 13B

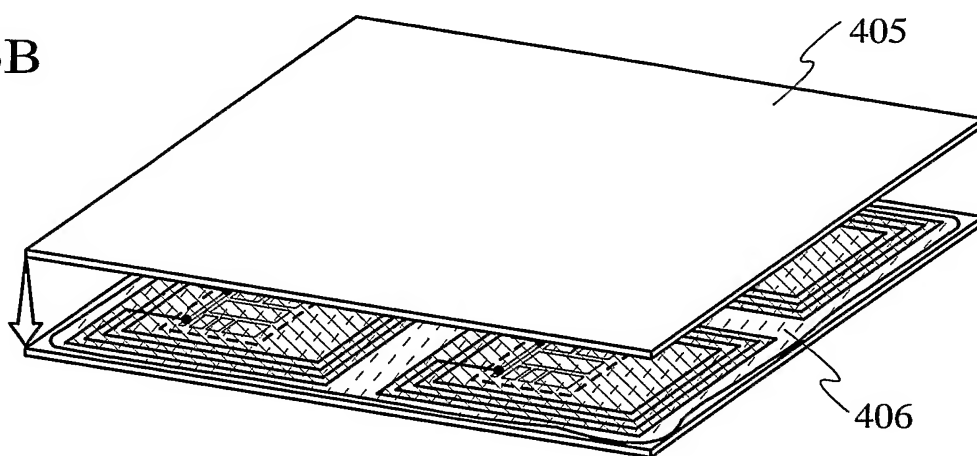


FIG. 13C

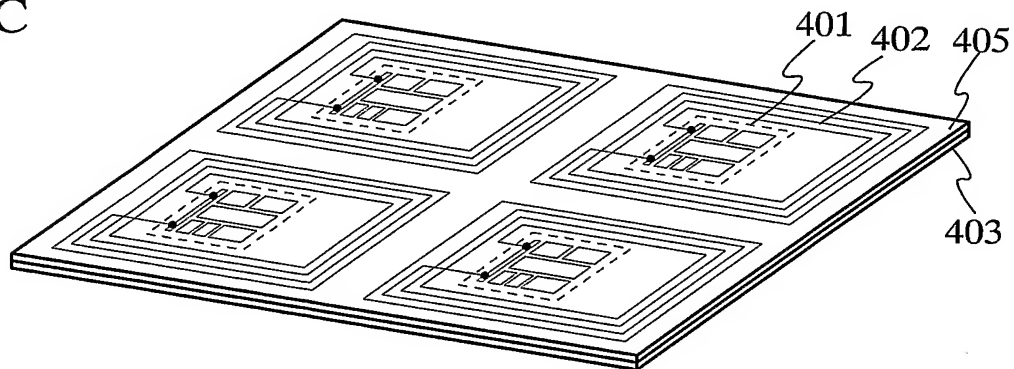


FIG. 13D

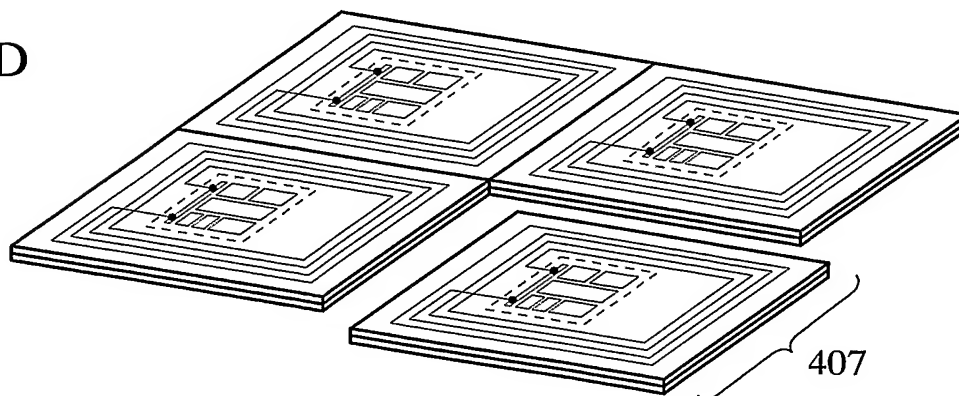


FIG. 14A

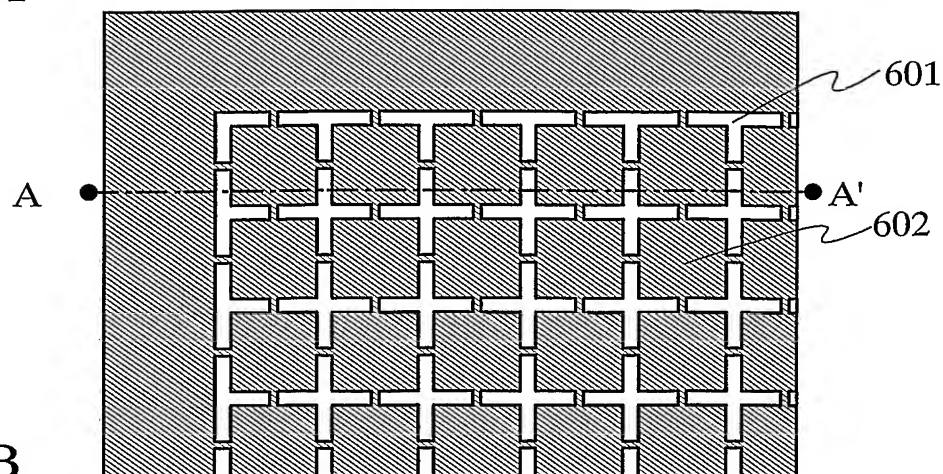


FIG. 14B

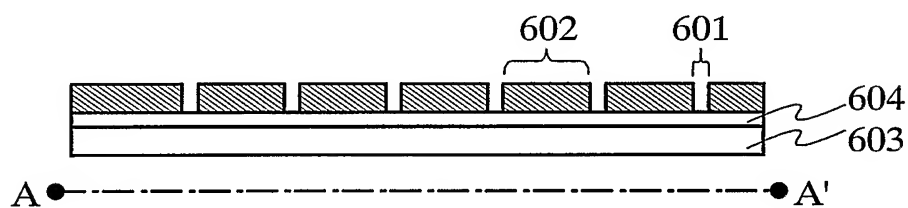


FIG. 14C

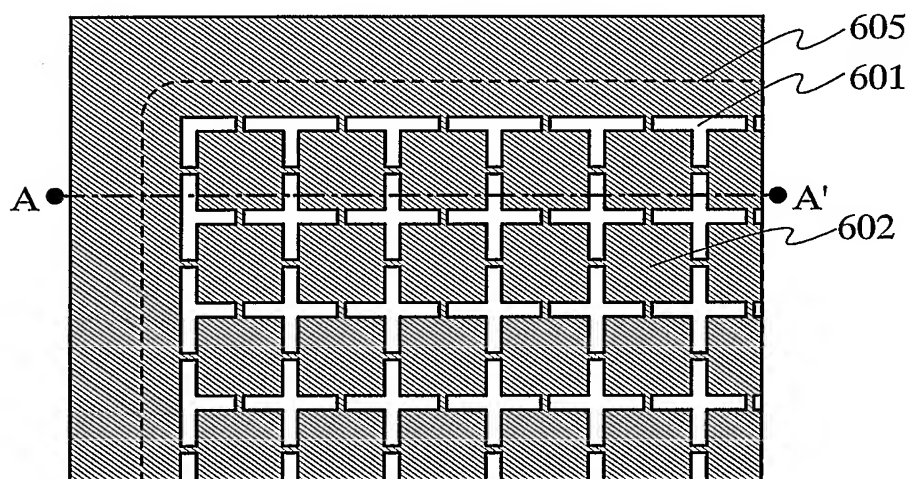


FIG. 14D

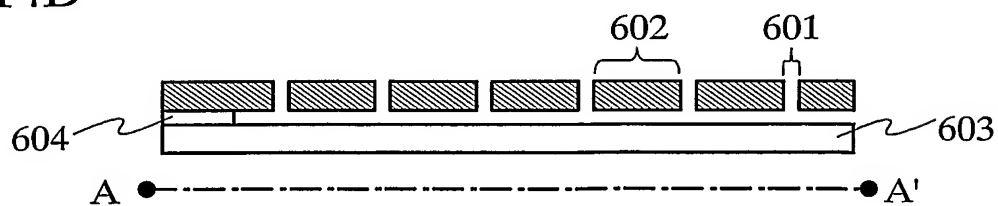


FIG. 15A

CHECK

Place ○○○○Bank
 ○○○○Branch

Amount ¥1,234,567 ※

Date YYYY/MM/DD
 ○○○○Inc

Place ○○○○ President○○○○

Stamp

1301

1302

FIG. 15B

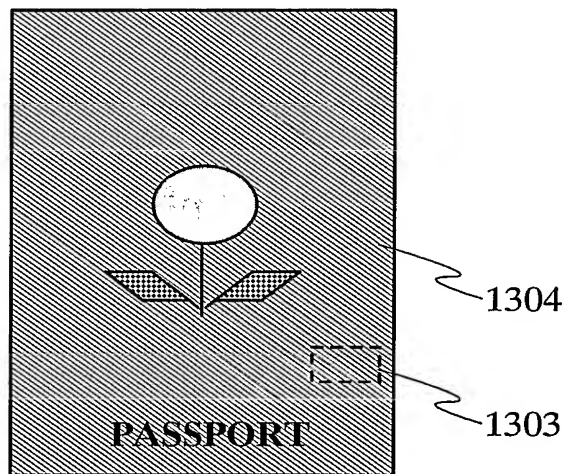
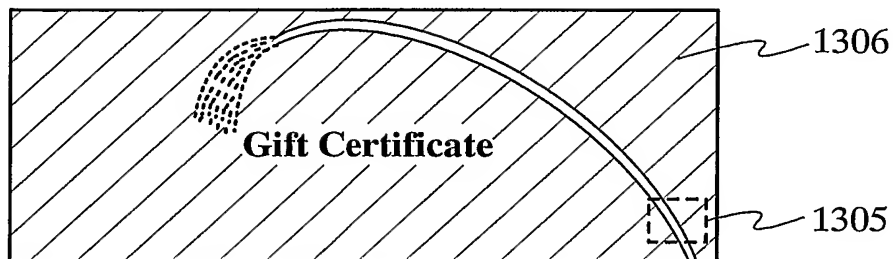


FIG. 15C



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FIG. 16A

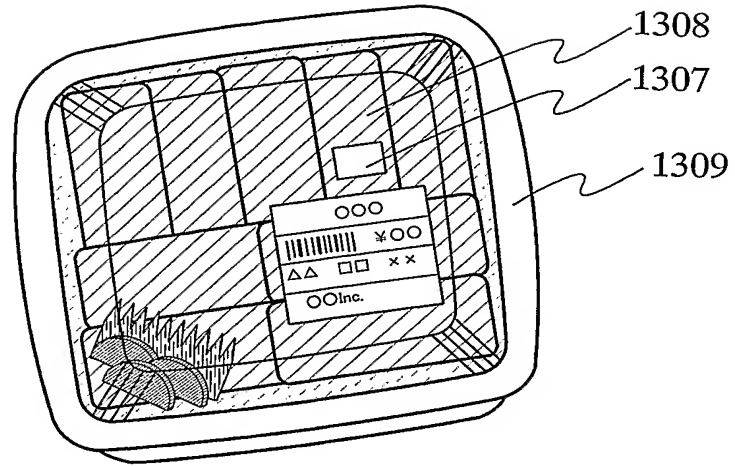


FIG. 16B

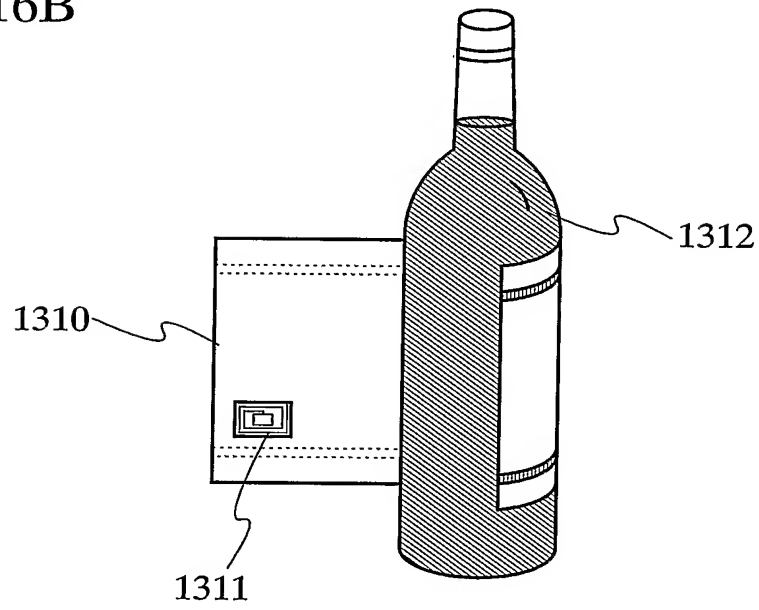
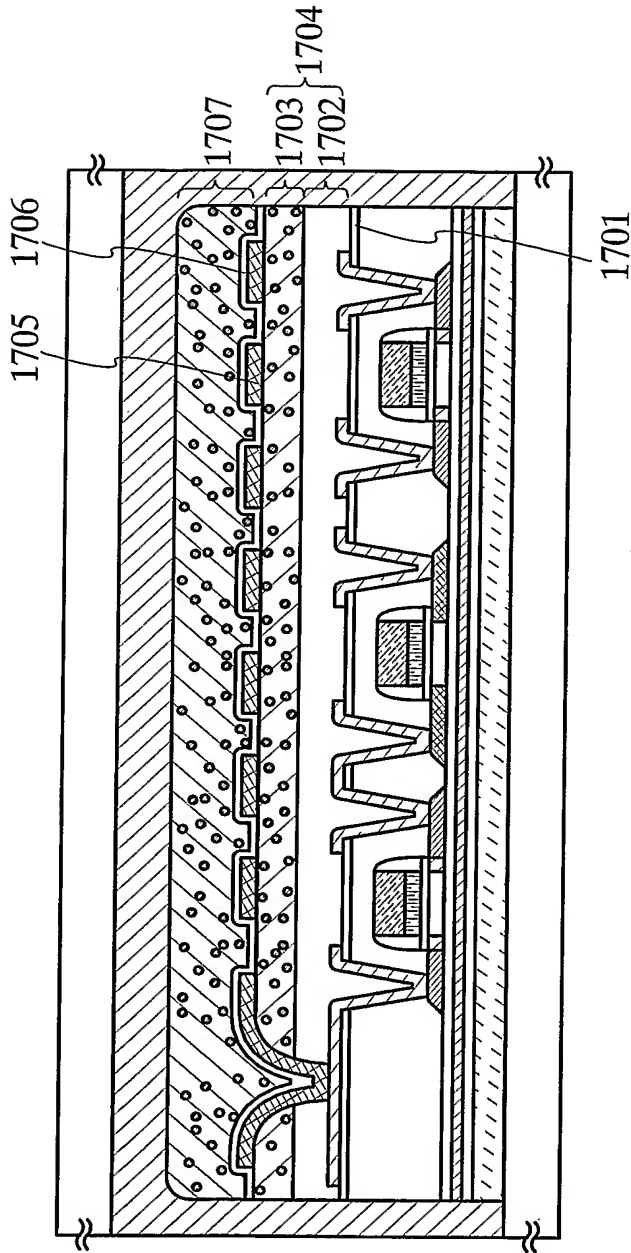


FIG. 17



EXPLANATION OF REFERENCE

100: integrated circuit, 101: antenna, 102: substrate, 103: cover material, 104: TFT, 105: conducting wire, 106: insulating layer, 107: broken line, 108: fine particles, 109: isolation insulating film, 110: insulator, 111: interlayer insulating film, 201: conductor, 202: conductor, 203: conductor, 204: conductor, 205: protective film, 301: isolation insulating film, 302: insulating layer, 303: insulating film, 304: isolation insulating film, 401: integrated circuit, 402: antenna, 403: substrate, 404: adhesive agent, 405: cover material, 406: adhesive agent, 407: ID chip, 500: substrate, 501: separation layer, 502: base film, 503: semiconductor film, 504: semiconductor film, 505: semiconductor film, 506: semiconductor film, 507: gate insulating film, 510: gate electrode, 511: gate electrode, 512: gate electrode, 513: resist, 514: resist, 516: low concentration impurity region, 517: low concentration impurity region, 518: resist, 519: high concentration impurity region, 520: insulating film, 522: sidewall, 523: sidewall, 524: sidewall, 525: resist, 527: high concentration impurity region, 528: high concentration impurity region, 529: TFT, 530: TFT, 531: TFT, 533: interlayer insulating film, 534: interlayer insulating film, 535: wiring, 536: wiring, 537: wiring, 538: wiring, 539: wiring, 540: interlayer insulating film, 541: antenna, 542: isolation insulating film, 543: protective layer, 546: groove, 547: adhesive agent, 548: substrate, 549: insulating layer, 550: insulator, 551: fine particles, 552: adhesive agent, 553: cover material, 570: substrate, 571: TFT, 572: TFT, 573: TFT, 574: base film, 575: cover material, 601: groove, 602: integrated circuit, 603: substrate, 604: separation layer, 605: broken line, 701: n-channel TFT, 702: p-channel TFT, 703: impurity region, 704: channel formation region, 705: semiconductor film, 706: gate insulating film, 707: gate electrode, 707a: conductive film, 707b: conductive film, 708: sidewall, 709: sidewall, 710: LDD region, 711: semiconductor film, 712: impurity region, 713: channel formation region, 721: n-channel TFT, 722: p-channel TFT, 728: sidewall, 729: sidewall, 741: n-channel TFT, 742: p-channel TFT, 743: impurity region, 744: channel formation region,

745: semiconductor film, 746: gate insulating film, 747: gate electrode, 748: channel protective film, 750: LDD region, 751: semiconductor film, 752: impurity region, 753: channel formation region, 900: antenna, 901: integrated circuit, 903: capacitor, 904: modulation circuit, 905: rectification circuit, 906: microprocessor, 907: memory, 908: switch, 909: demodulation circuit, 1301: check, 1302: ID chip, 1303: ID chip, 1304: passport, 1305: ID chip, 1306: gift certificate, 1307: ID chip, 1308: packing material, 1309: boxed meal, 1310: label, 1311: ID chip, 1312: product, 1401: TFT, 1402: semiconductor film, 1403: gate insulating film, 1404: gate electrode, 1405: interlayer insulating film, 1406: interlayer insulating film, 1407: wiring, 1408: antenna, 1409: isolation insulating film, 1410: insulating layer, 1411: TFT, 1412: semiconductor film, 1413: gate insulating film, 1414: gate electrode, 1418: antenna, 1420: insulating layer, 1701: interlayer insulating film, 1702: insulating film, 1703: insulating film, 1704: interlayer insulating film, 1705: antenna, 1706: isolation insulating film, 1707: insulating layer,